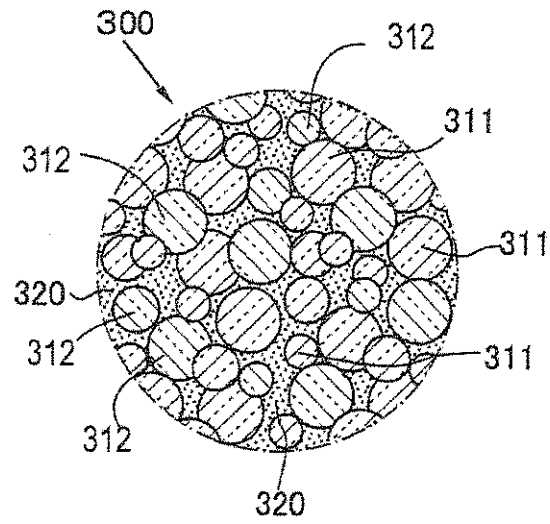
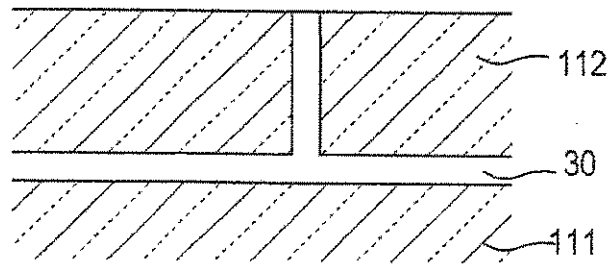


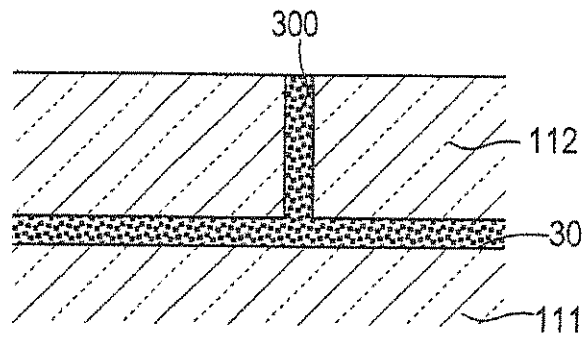
*FIG. 1*

(A)



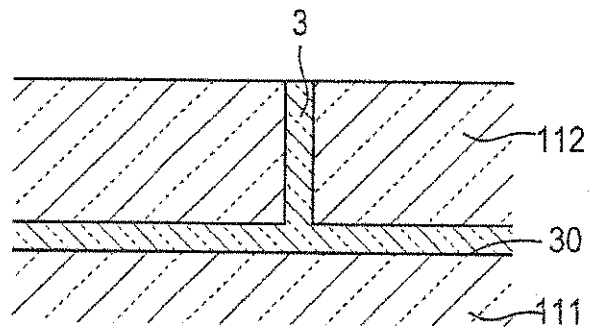
PREPARATION

(B)



POURING OF INSULATING PASTE
(PASTE CONTAINS INSULATING PARTICLES (SiO_2),
Si PARTICLES AND ORGANIC Si COMPOUND)

(C)



HARDENING

FIG.2

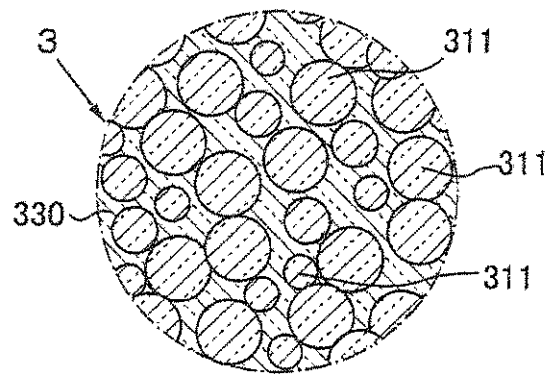
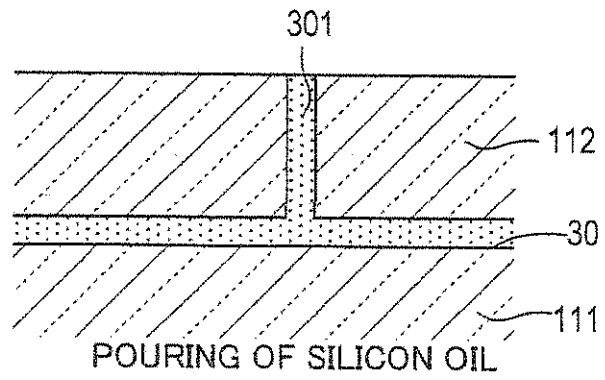
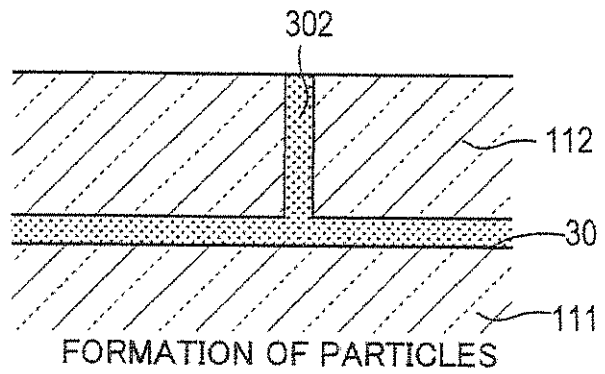


FIG.3

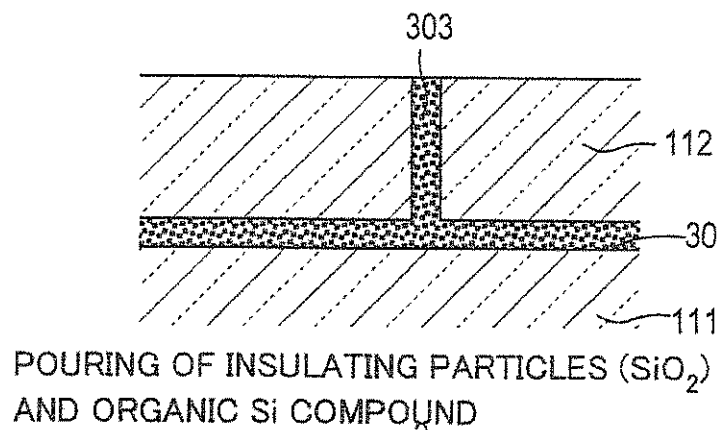
(A)



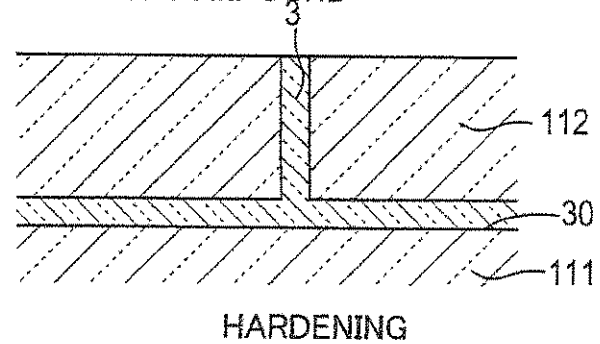
(B)

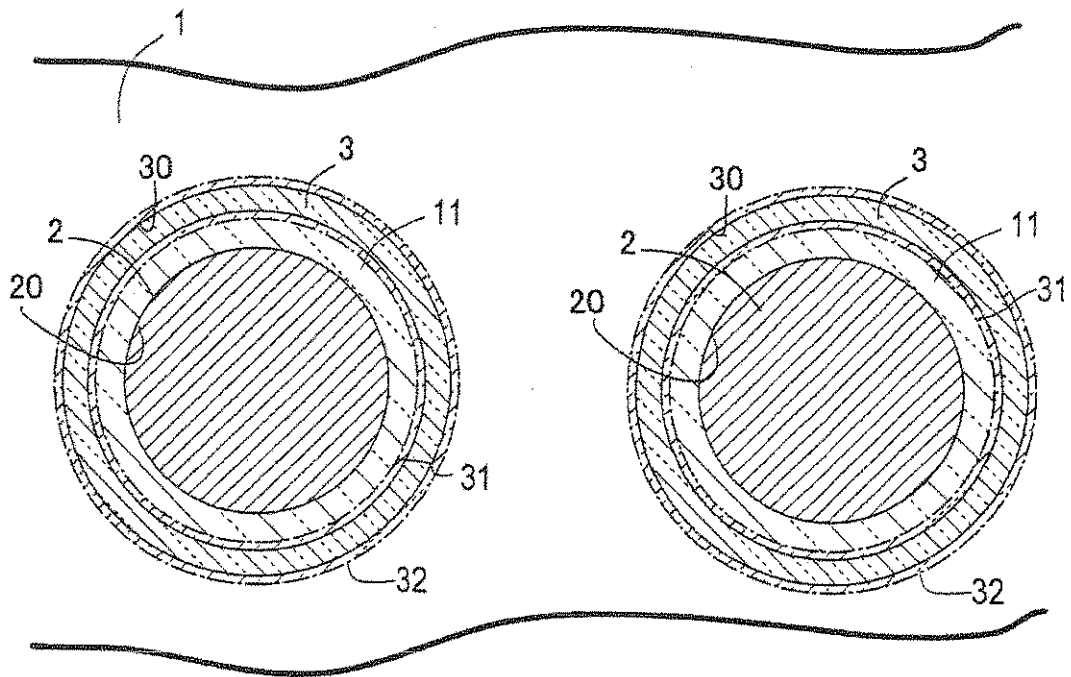


(C)



(D)

**FIG.4**

*FIG. 5*

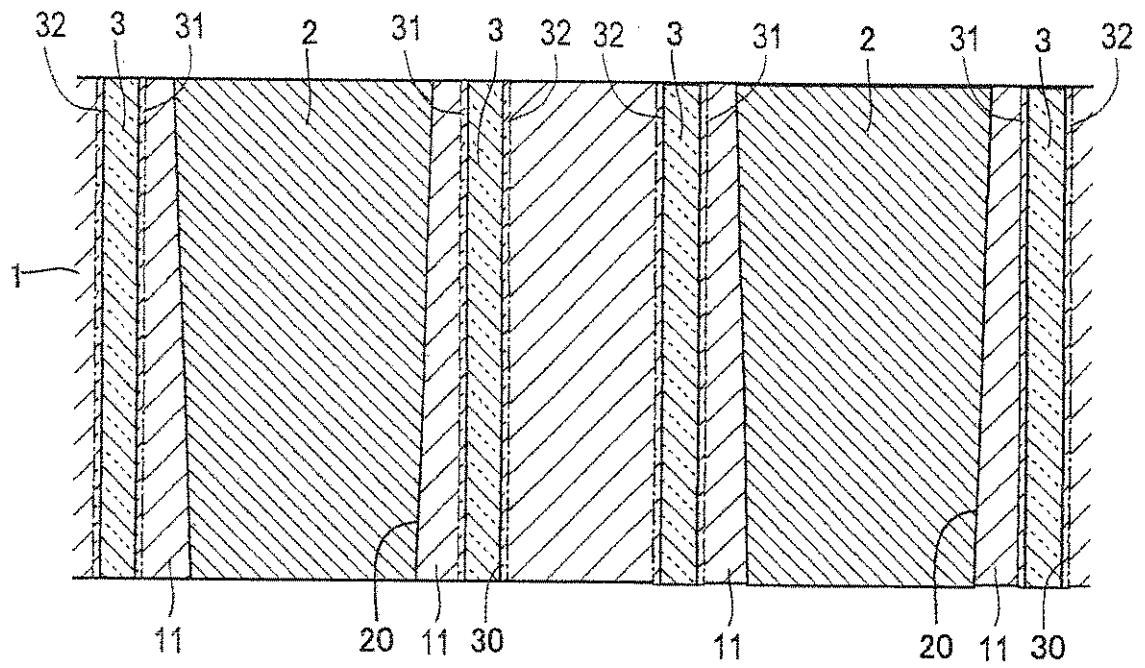
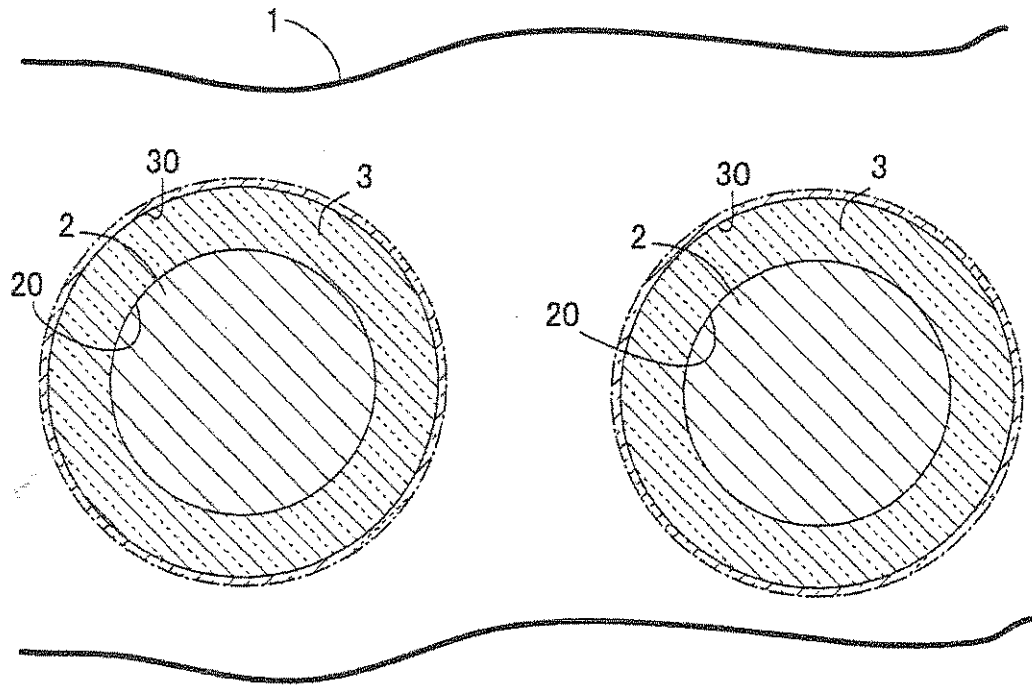
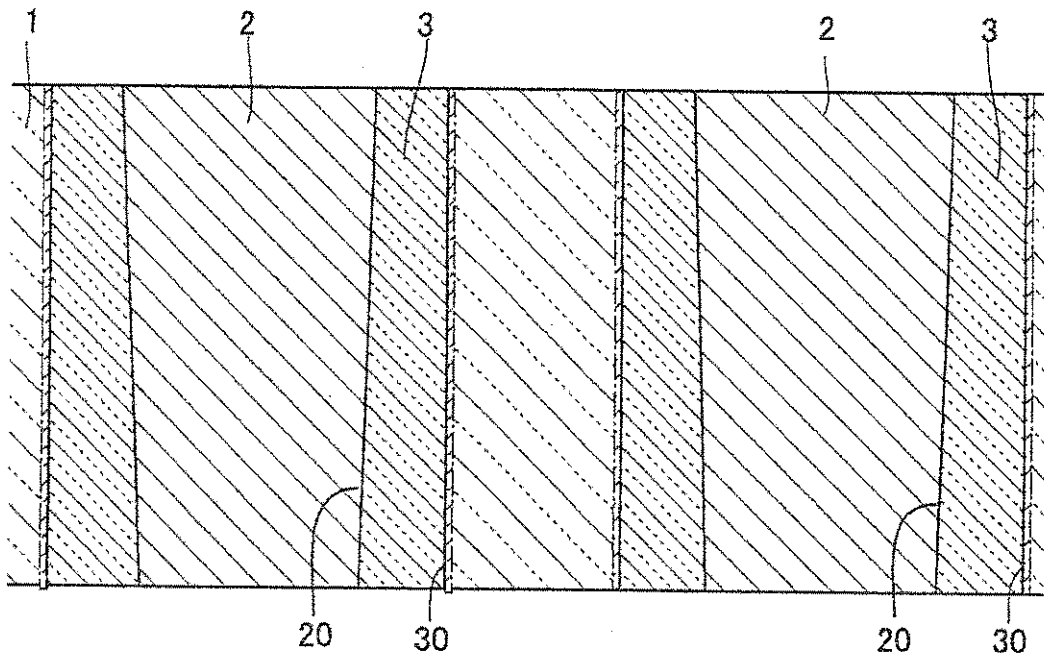


FIG. 6

**FIG. 7**

*FIG.8*